

***Examiner's amendment***

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Mr. Kent E. Baldauf on 26 June 2008.

The application has been amended as follows:

In of the amendments to the claims filed 16 August 2007

Cancel claim 17 and insert therefore:

17. A method for grinding a semiconductor wafer comprising:

allowing a semiconductor wafer, on a circuit surface of which bumps are formed, to be in a surface-protected form wherein an adhesive layer having an opening portion with no adhesive corresponding to a portion of the wafer where the bumps are formed and an adhesive portion corresponding to an outer peripheral portion of the wafer where bumps are not formed is formed and a base sheet is laminated on the adhesive layer so as to cover the opening portion of the adhesive layer,

placing the semiconductor wafer of the surface-protected form on a fixing table in such a manner that the base sheet faces the fixing table, and grinding a back surface of the semiconductor wafer, wherein:

the semiconductor wafer is allowed to have the surface-protected form by:

supplying the adhesive layer in such manner that both surfaces of the adhesive

layer are laminated with release films of light-releasable type and heavy-releasable type, wherein the adhesive layer and the release film of light-releasable type are punched to form the opening portion, so that the adhesive layer is supported on the release film of heavy-releasable type,

peeling the release film of light-releasable type while adhering the exposed surface of the adhesive layer to the base sheet, and

peeling the release film of heavy-releasable type while adhering the exposed surface of the adhesive layer to the outer peripheral portion of the wafer.

Cancel claims 18-19.

Claim 22, line 20, change "both surface" to --both surfaces--.

### ***Reasons for Allowance***

2. The following is an examiner's statement of reasons for allowance: prior art of record considered as a whole alone or in combination neither anticipates nor renders obvious, adhesive layer on the side facing the base sheet is an adhesive having strong adhesion strength and other adhesive layer on the side facing the wafer is an energy ray-curable adhesive which is cured by irradiation with energy rays to exhibit removability, in combination with the rest of claims 12 and 16; prior art of record considered as a whole alone or in combination neither anticipates nor renders obvious, supply the adhesive layer in such manner that both surfaces of the adhesive layer are laminated with release films of light-releasable type and heavy-releasable type, wherein the adhesive layer and the release film of light-releasable type are punched to form the

opening portion so that the adhesive layer is supported on the release film of heavy releasable type, in combination with the rest of claims 17 and 22.

3. Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

### ***Conclusion***

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dung Van Nguyen whose telephone number is 571-272-4490. The examiner can normally be reached on PHP Program.

5. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Joseph J. Hail can be reached on 571-272-4485. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

6. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Art Unit: 3723

/Dung Van Nguyen/

Primary Examiner, Art Unit 3723

June 26, 2008